



Material Content Data Sheet



Sales Product Name		BGT 24ATR12 E6433		Issued		19. January 2018		
MA#		MA001103324						
Package		PG-VQFN-32-9		Weight*		55.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.375	4.27	4.27	42704	42704
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		145	
	non noble metal	zinc	7440-66-6	0.032	0.06		582	
	non noble metal	iron	7439-89-6	0.647	1.16		11639	
wire	non noble metal	copper	7440-50-8	26.284	47.26	48.49	472587	484953
	noble metal	gold	7440-57-5	0.367	0.66	0.66	6605	6605
	encapsulation	organic material	carbon black	1333-86-4	0.070	0.13		1252
encapsulation	plastics	epoxy resin	-	2.948	5.30		52999	
	inorganic material	silicondioxide	60676-86-0	20.192	36.31	41.74	363063	417314
leadfinish	non noble metal	tin	7440-31-5	1.435	2.58	2.58	25805	25805
plating	noble metal	silver	7440-22-4	0.555	1.00	1.00	9979	9979
glue	plastics	epoxy resin	-	0.162	0.29		2907	
	noble metal	silver	7440-22-4	0.541	0.97	1.26	9733	12640
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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